



Title of Change:	Fab Transfer from Fab2 to Gresham for OPN NCV70627DQ001R2G. Also updated Leadframe + mold compound.
Proposed Changed Material First Ship Date:	26 Nov 2021 or earlier if approved by customer
Current Material Last Order Date:	30 Jun 2021 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	25 Nov 2021 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local ON Semiconductor Sales Office or Alicia.Tuckett@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com> . Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	18 Jun 2021
PPAP Availability Date:	N/A
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Dimitri.Tack@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Process - Assembly	Change of mold compound, Change of leadframe base material, Change of product marking



Description and Purpose:

Transfer to ON Semiconductor Gresham, Oregon as wafer fab location (I3T technology, 200 mm fab), currently manufactured in Fab2, Oudenaarde, Belgium (150 mm fab) for the NCV70627DQ001R2G. Addition of Polyimide and the change of leadframe and mold compound will be done as part of our global quality continuous improvement program. Items Changes 3 and 4 are minor changes to improve performance and manufacturability. For traceability, the marking will be updated with a Fab indicator, "G" for Gresham. A new OPN will also be created, NCV70627DQ002AR2G.

	Before Change Description	After Change Description
Wafer Fab	Fab2, Oudenaarde, Belgium (150 mm fab)	Gresham, Oregon (200 mm fab)
LeadFrame	N42423E711	N42423E814 Etched RuPPF
Mold Compound	N21117R009 MC EME G600	N53479E009 Sumitomo G700LS
Other Change	No Polyimide	Addition of Polyimide
Other Change	No ring bond pads	Ring bond pads

	From	To
Product marking change	Without Fab indicator	Fab indicator, "G" for Gresham
OPN	NCV70627DQ001R2G	NCV70627DQ002AR2G

Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change Quality Improvement
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Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.
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Sites Affected:	
ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Gresham, Oregon	None
ON Semiconductor Carmona, Philippines	

Marking of Parts/ Traceability of Change:	For traceability, the marking will be updated with a Fab indicator, "G" for Gresham
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Reliability Data Summary:

NOTE: AEC-1pager is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NCV70627DQ001R2G	NCV70627DQ002AR2G	0C627-603